

**AMENDMENTS TO THE CLAIMS**

**Claims 1-90 (Canceled without prejudice or disclaimer).**

91. (Currently Amended) A semiconductor device comprising:

- (1) a semiconductor pellet of a quadrilateral shape having bonding pads formed in a main surface thereof, said semiconductor pellet having a first pair of opposed edges extending in a first direction and a second pair of opposed edges extending in a second direction which intersects said first direction, said bonding pads being arranged in said first direction to form a row of bonding pads;
- (2) a substrate, formed of a glass fiber impregnated with resin, having a first surface, a second surface opposite to said first surface, electrode pads formed on said second surface and a slit passing through said substrate from said first surface to said second surface and extending in said first direction, said semiconductor pellet being disposed on said first surface of said substrate such that said main surface of said semiconductor pellet is faced to said first surface of said substrate and said row of binding pads is arranged in said slit in a plane view, said electrode pads including first electrode pads arranged at one side of said slit and second electrode pads arranged at the other side of said slit in said second direction;
- (3) bonding wires electrically connecting said electrode pads of said substrate with said bonding pads of said semiconductor pellet via said slit, said bonding

- wires including first bonding wires connected to said first electrode pads and second bonding wires connected to said second electrode pads;
- (4) bump electrodes being disposed on said second surface of said substrate and being electrically connected to said electrode pads of said substrate, said bump electrodes including first bump electrodes electrically connected to said first electrode pads and arranged at said one side of said slit and second bump electrodes electrically connected to said second electrode pads and arranged at the other side of said slit, said first and second bump electrodes being arranged to overlap with said semiconductor pellet in said plane view respectively; and
- (5) a resin sealing body sealing said bonding wires and said main surface of said semiconductor pellet exposed from said slit;
- (6) wherein a height of said bump electrodes is greater than a thickness of said resin sealing body from said second surface of said substrate in a thickness direction of said semiconductor pellet.

96. (Currently Amended) A semiconductor device comprising:

- (1) a semiconductor pellet of a quadrilateral shape having bonding pads formed in a main surface thereof, said semiconductor pellet having a first pair of opposed edges extending in a first direction and a second pair of opposed edges extending in a second direction which intersects said first direction, said bonding pads being arranged in said first direction;

- (2) a substrate, formed of a glass fiber impregnated with resin, having a first surface, a second surface opposite to said first surface, electrode pads formed on said second surface and a slit passing through said substrate from said first surface to said second surface and extending in said first direction, said semiconductor pellet being disposed on said first surface of said substrate such that said main surface of said semiconductor pellet is faced to said first surface of said substrate and said binding pads are arranged in said slit in a plane view, said electrode pads including first electrode pads arranged at one side of said slit and second electrode pads arranged at the other side of said slit in said second direction;
- (3) bonding wires electrically connecting said electrode pads of said substrate with said bonding pads of said semiconductor pellet via said slit, said bonding wires including first bonding wires connected to said first electrode pads and second bonding wires connected to said second electrode pads;
- (4) bump electrodes being disposed on said second surface of said substrate and being electrically connected to said electrode pads of said substrate, said bump electrodes including first bump electrodes electrically connected to said first electrode pads and arranged at said one side of said slit and second bump electrodes electrically connected to said second electrode pads and arranged at the other side of said slit, said first and second bump electrodes being arranged to overlap with said semiconductor pellet in said plane view respectively; and

(5) a resin sealing body sealing said bonding wires and said main surface of said semiconductor pellet exposed from said slit,

(6) wherein a height of said bump electrodes is greater than a thickness of said resin sealing body from said second surface of said substrate in a thickness direction of said semiconductor pellet.

**Claims 102-103 (Canceled without prejudice or disclaimer).**